

Features

- Ultra-Small Surface Mount Package
- Fast Switching Speed
- For General Purpose Switching Applications
- High Conductance
- **Lead Free/RoHS Compliant (Note 1)**
- **"Green" Device (Notes 2 and 3)**

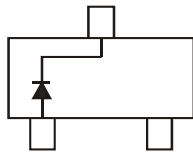
Mechanical Data

- Case: SOT-523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagrams Below
- Weight: 0.002 grams (approximate)

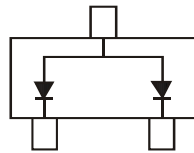
SOT-523



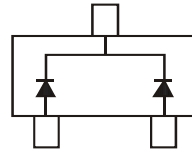
TOP VIEW



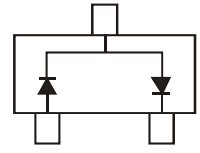
MMBD4448HT Marking: A3



MMBD4448HTA Marking: A6



MMBD4448HTC Marking: A7



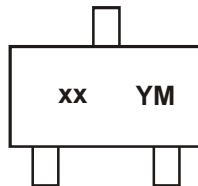
MMBD4448HTS Marking: AB

Ordering Information (Note 4)

Part Number	Case	Packaging
MMBD4448HT-7-F	SOT-523	3000/Tape & Reel
MMBD4448HTA-7-F	SOT-523	3000/Tape & Reel
MMBD4448HTC-7-F	SOT-523	3000/Tape & Reel
MMBD4448HTS-7-F	SOT-523	3000/Tape & Reel

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
 3. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



xx = Product Type Marking Code (See Page 1 Diagrams)
 YM = Date Code Marking
 Y = Year (ex: N = 2002)
 M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit	
Non-Repetitive Peak Reverse Voltage	V_{RM}	100	V	
Peak Repetitive Reverse Voltage	V_{RRM}	80	V	
Working Peak Reverse Voltage	V_{RWM}			
DC Blocking Voltage	V_R			
RMS Reverse Voltage	$V_{R(RMS)}$	57	V	
Forward Continuous Current (Note 5)	I_{FM}	500	mA	
Average Rectified Output Current (Note 5)	I_O	250	mA	
Non-Repetitive Peak Forward Surge Current	I_{FSM}	@ $t = 1.0\mu\text{s}$	4.0	A
		@ $t = 1.0\text{s}$	1.0	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	150	mW
Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	80	—	V	$I_R = 2.5\mu\text{A}$
Forward Voltage	V_F	0.62	0.72	V	$I_F = 5.0\text{mA}$
		—	0.855		$I_F = 10\text{mA}$
		—	1.0		$I_F = 100\text{mA}$
		—	1.25		$I_F = 150\text{mA}$
Leakage Current (Note 6)	I_R	—	100	nA	$V_R = 70\text{V}$
		—	50	μA	$V_R = 75\text{V}, T_J = 150^\circ\text{C}$
		—	30	μA	$V_R = 25\text{V}, T_J = 150^\circ\text{C}$
		—	25	nA	$V_R = 20\text{V}$
Total Capacitance	C_T	—	3.5	pF	$V_R = 6\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	—	4.0	ns	$V_R = 6\text{V}, I_F = 5\text{mA}$

Notes: 5. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
 6. Short duration pulse test used to minimize self-heating effect.

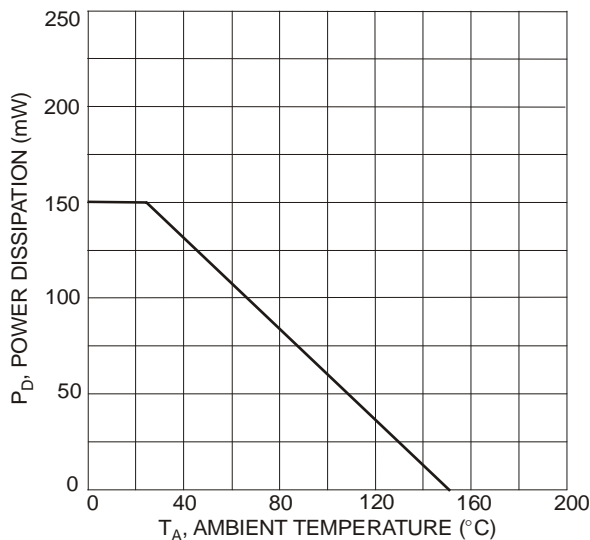


Fig. 1 Power Derating Curve, Total Package (Note 5)

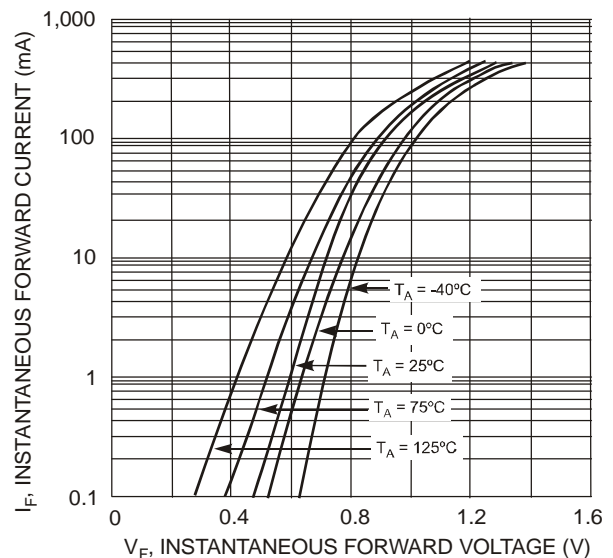


Fig. 2 Typical Forward Characteristics, Per Element

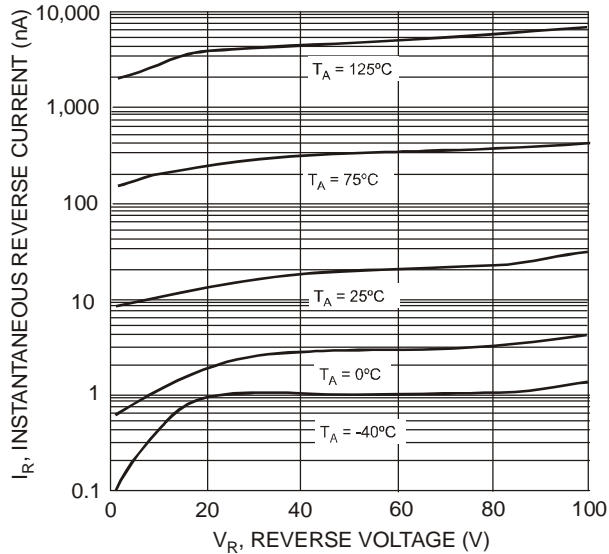


Fig. 3 Typical Reverse Characteristics, Per Element

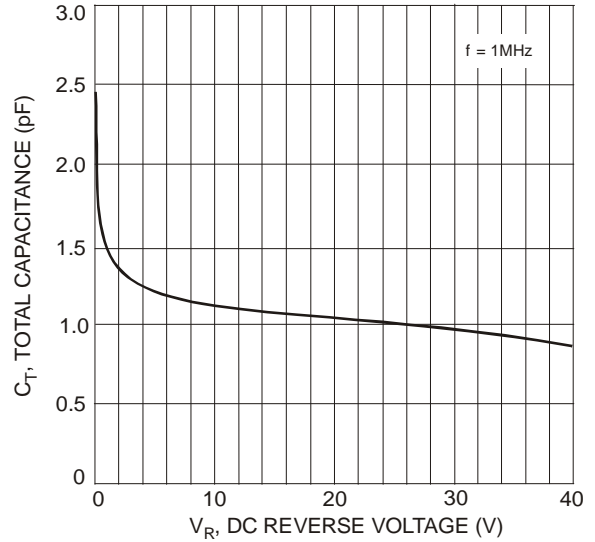
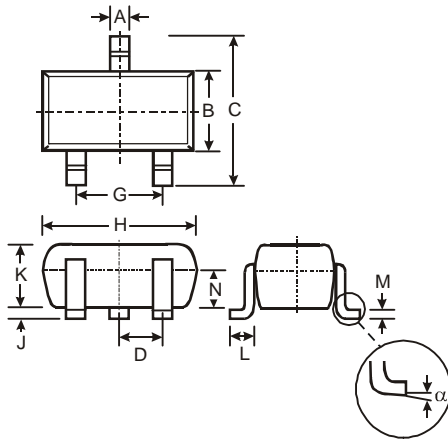


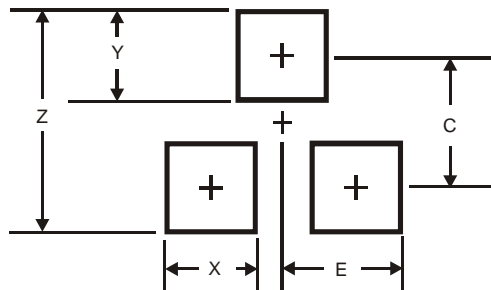
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions



SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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